



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD112-B1-02EL E6327		<b>Issued</b>		2. August 2018		
<b>MA#</b>		MA001190844						
<b>Package</b>		PG-TSLP-2-20		<b>Weight*</b>		0.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.06		584	
	noble metal	gold	7440-57-5	0.001	0.23		2262	
	inorganic material	silicon	7440-21-3	0.010	1.68	1.97	16763	19609
leadframe	non noble metal	nickel	7440-02-0	0.241	40.24	40.24	402432	402432
wire	noble metal	gold	7440-57-5	0.005	0.89	0.89	8945	8945
encapsulation	organic material	carbon black	1333-86-4	0.002	0.28		2757	
	plastics	epoxy resin	-	0.048	8.00		79954	
	inorganic material	silicondioxide	60676-86-0	0.280	46.86	55.14	468699	551410
leadfinish	noble metal	gold	7440-57-5	0.010	1.74	1.74	17426	17426
plating	noble metal	palladium	7440-05-3	0.000	0.01		69	
	noble metal	gold	7440-57-5	0.000	0.01	0.02	109	178
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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